

**Heatsink**

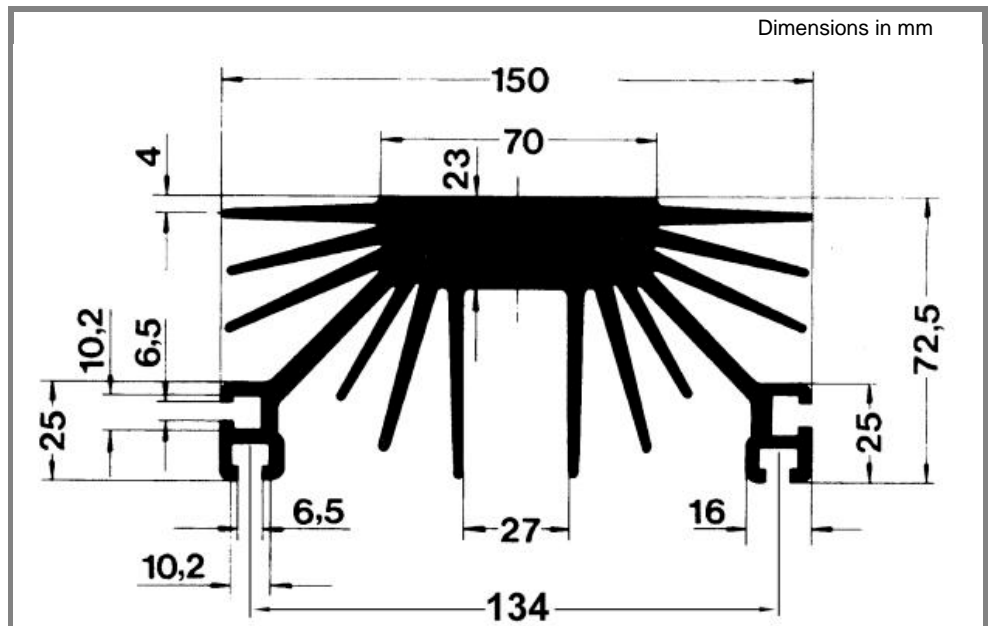
Standard lengths	n	b / d Ø mm	R <sub>thca</sub> natural cooling K/W	R <sub>thca</sub> V <sub>air</sub> /t = 600 m <sup>3</sup> /h K/W	w kg
2x P 8/180		19 ± 1	0,32 (200W)	0,095	3,45
		25 ± 2	0,31 (200W)	0,077	
		33 ± 2	0,30 (200W)	0,067	
		48 ± 2	0,30 (200W)	0,055	
P 8/375 + 2x P 8/180		19 ± 1		0,109	7
		25 ± 2		0,094	
		33 ± 2		0,082	
		48 ± 2		0,066	

For capsule devices

P 8

**Features**

- Intended for double-sided cooling of capsule devices with diameters upto 63mm
- Mainly for natural cooling at high currents (e.g. for railway substations, power supplies for telecommunication)
- Available in various lengths



P 8 general profile dimensions (w = 9,6 kg/m)

Dimensions in mm

**Mounting clamp 'MC' for double sided cooling**

**Insulating sleeve for bolts for double-side cooled capsules**

**Insulating ducting for P 8**

**Fan SKF 9-230-01 + Insulating base**

(Please contact SEMIKRON for further details on the above accessories)

P 8 standard accessories

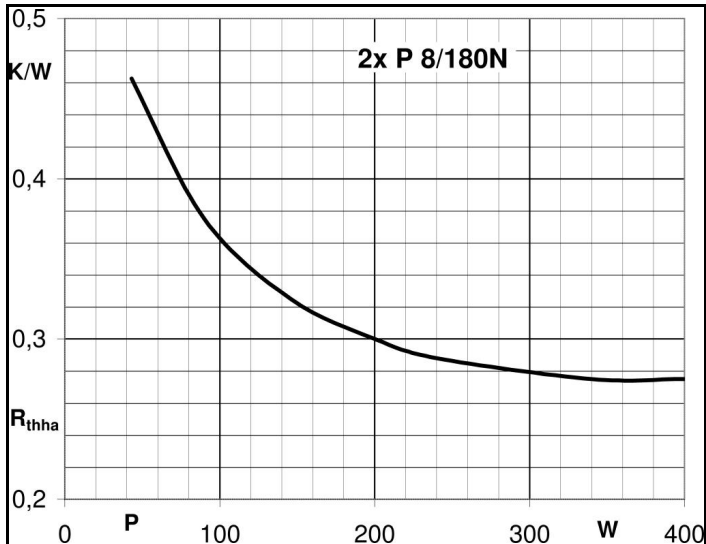


Fig.1 Thermal resistance vs. dissipated power

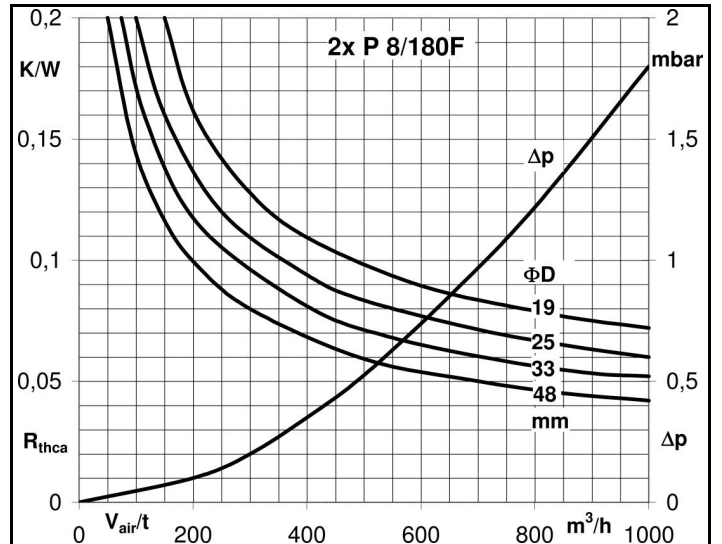


Fig.5a Thermal resistance and pressure drop vs. air flow

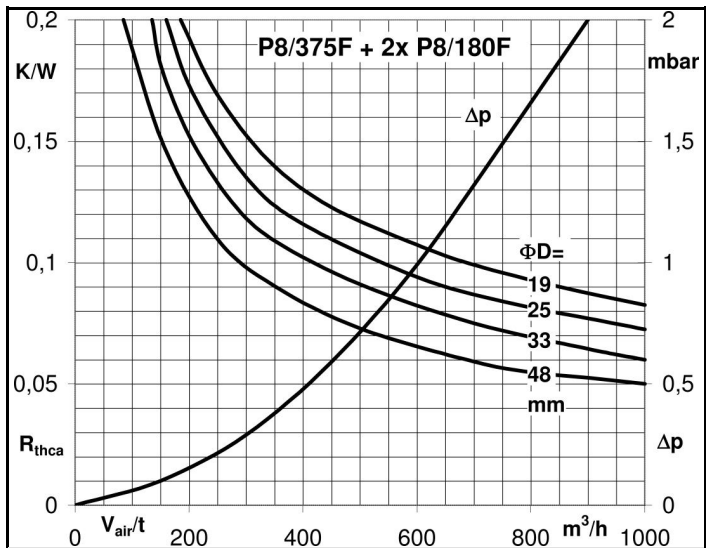


Fig.5b Thermal resistance and pressure drop vs. air flow

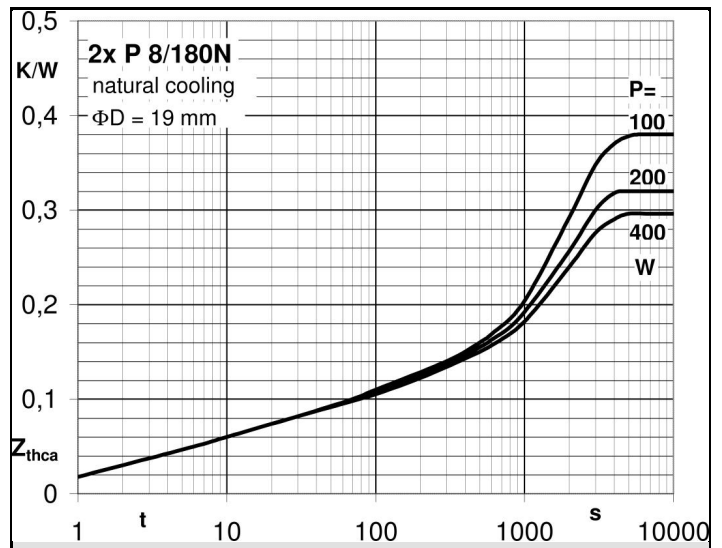


Fig.9a Transient thermal impedance vs. time

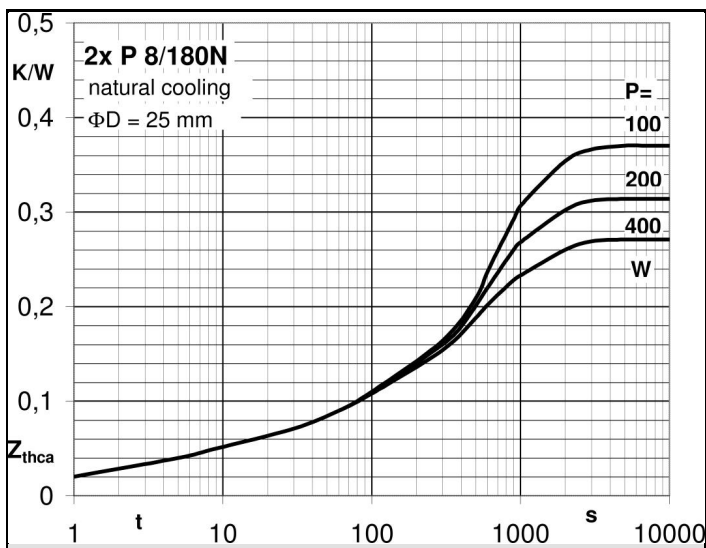


Fig.9b Transient thermal impedance vs. time

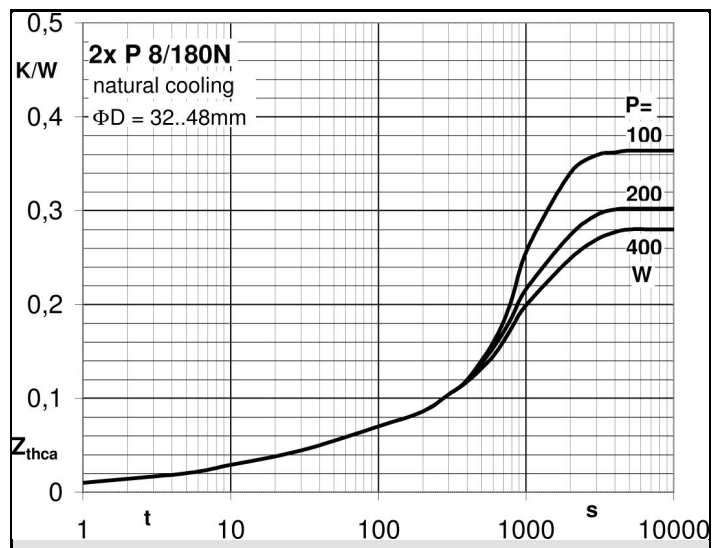


Fig.9c Transient thermal impedance vs. time

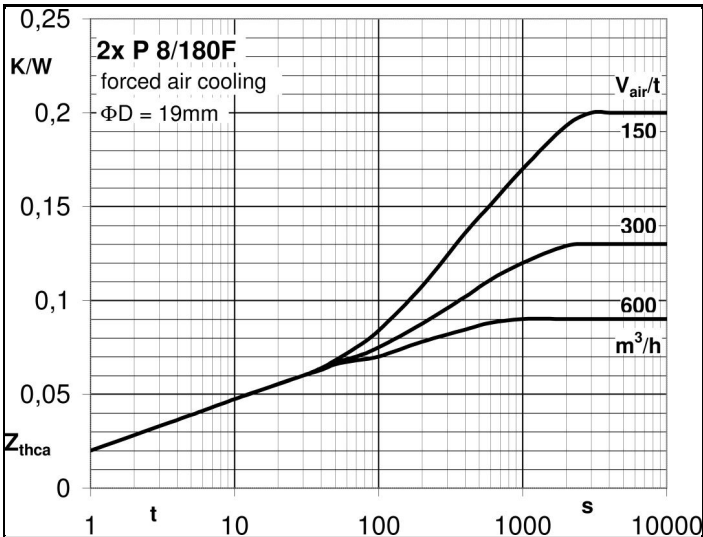


Fig.11a Transient thermal impedance vs.time

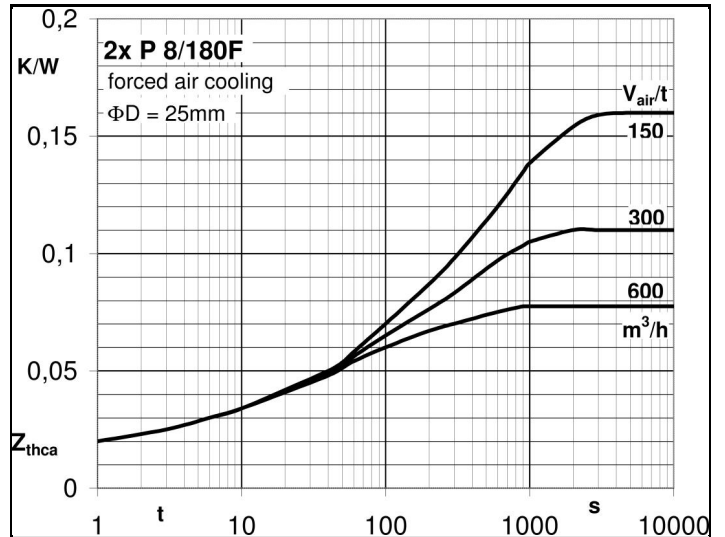


Fig.11b Transient thermal impedance vs.time

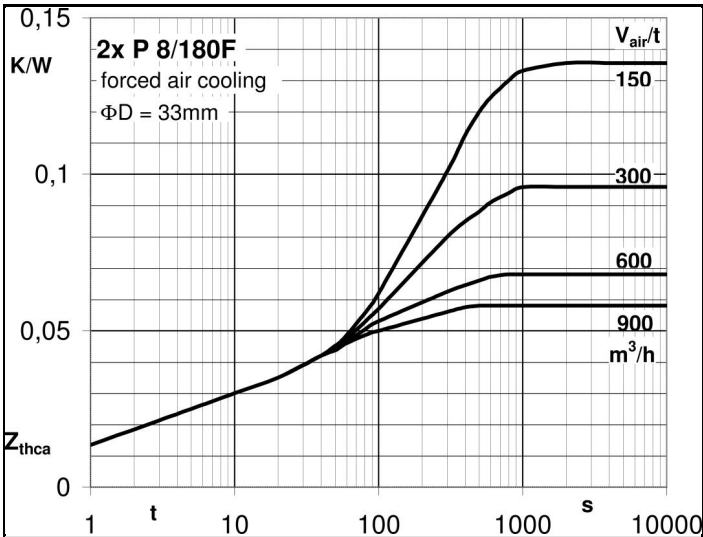


Fig.11c Transient thermal impedance vs.time

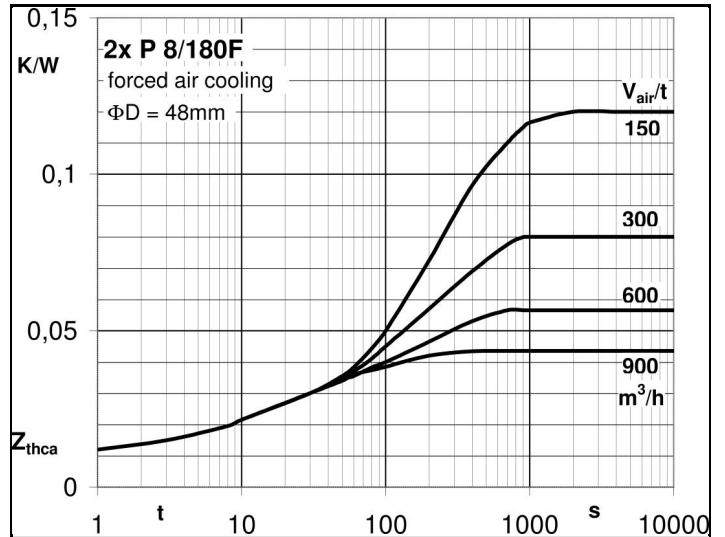


Fig.11d Transient thermal impedance vs.time

